

PROCESSING APPARATUS

ABSTRACT

A processing apparatus includes a rotatable turntable and four chuck tables disposed on the turntable. When the turntable with the four chuck tables disposed thereon is intermittently turned about its central axis, the wafer held on each of the chuck tables is moved to and positioned in a first processing position, a second processing position, and a third processing position where the wafer is processed. Three types of processing processes are able to be carried out on the wafers without the wafers being spaced from holding surfaces of the chuck tables.

[FIG. 1]